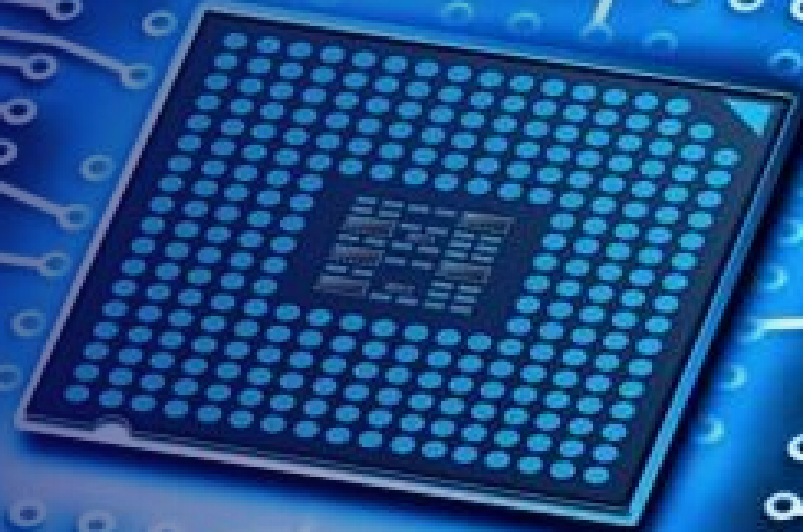


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SEMICONDUCTOR

Introduction to TOLT Package

JUNE 2024

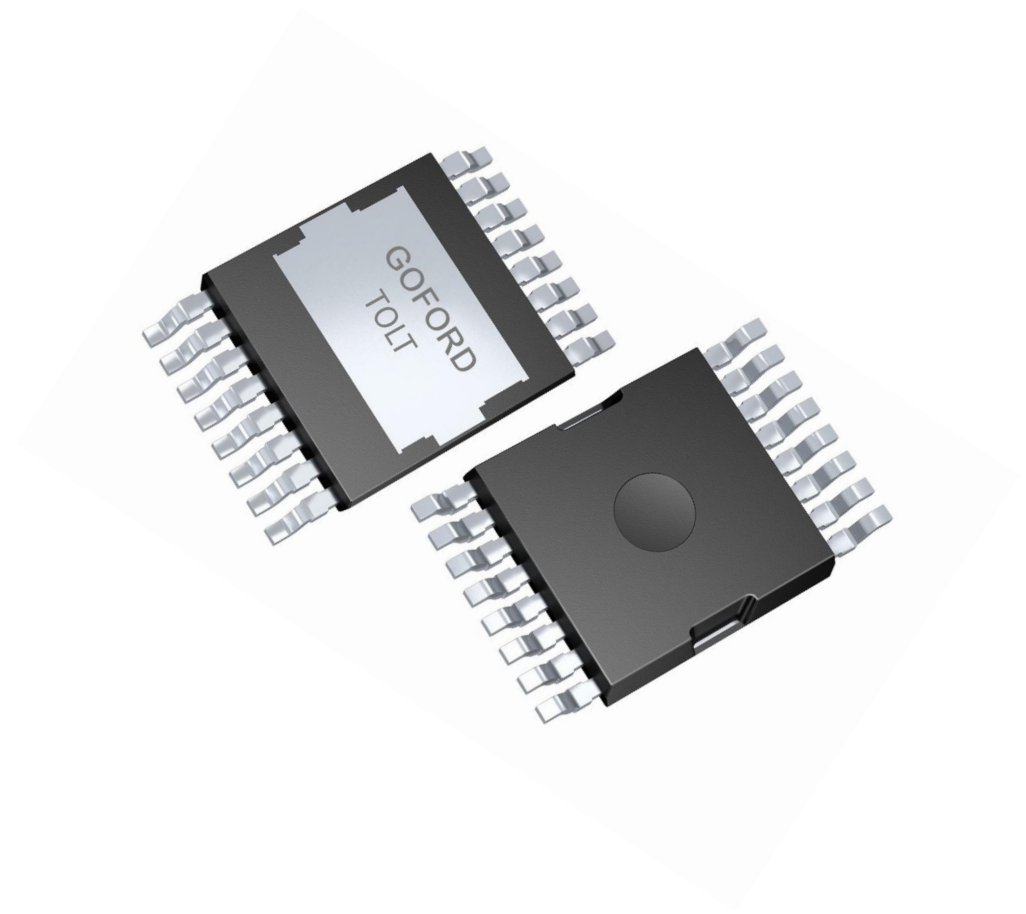


Introduction

- Features
- Advantages
- Dimension

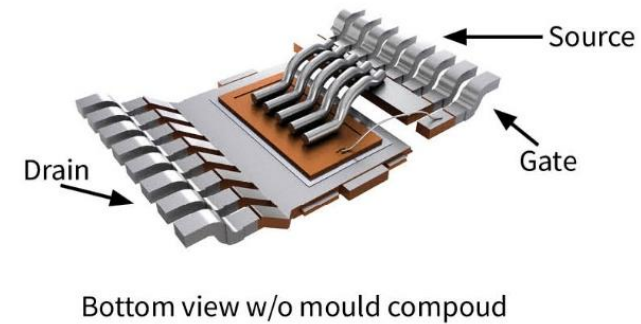
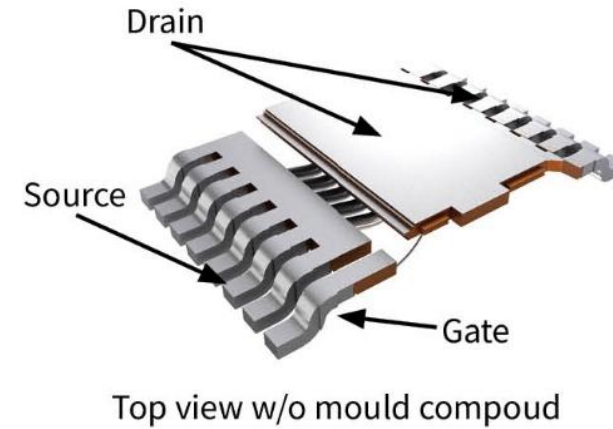
Application

Development



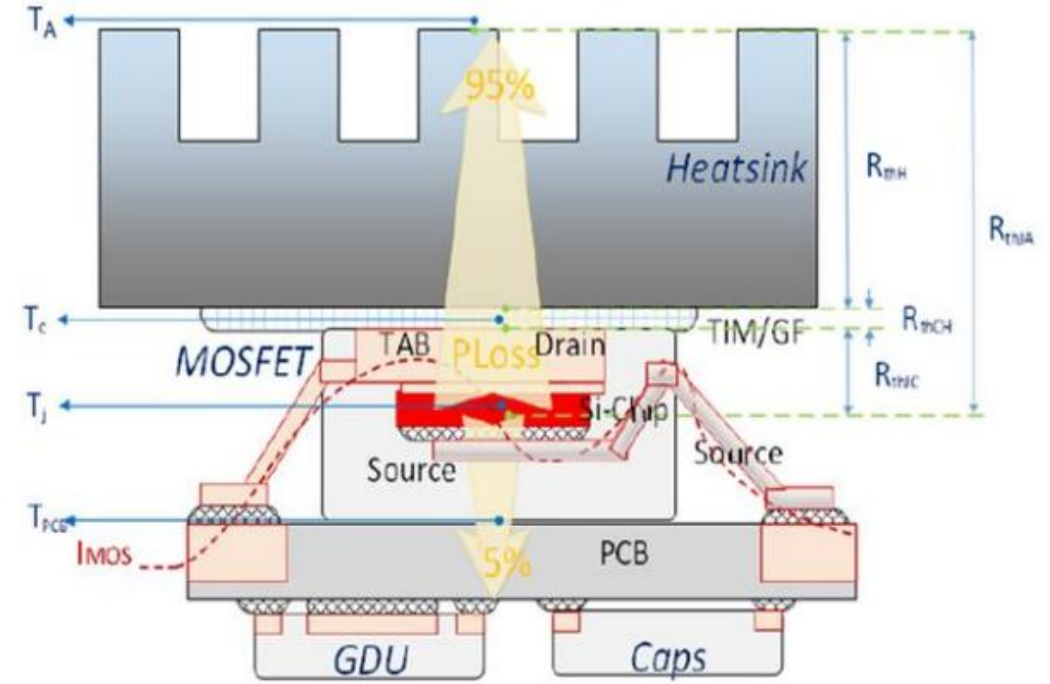
Features

- Low $R_{DS(on)}$
- High current rating $>300\text{ A}$
- Top-side cooling
- Negative stand-off
- Sn-free exposed pad
- Gull wing



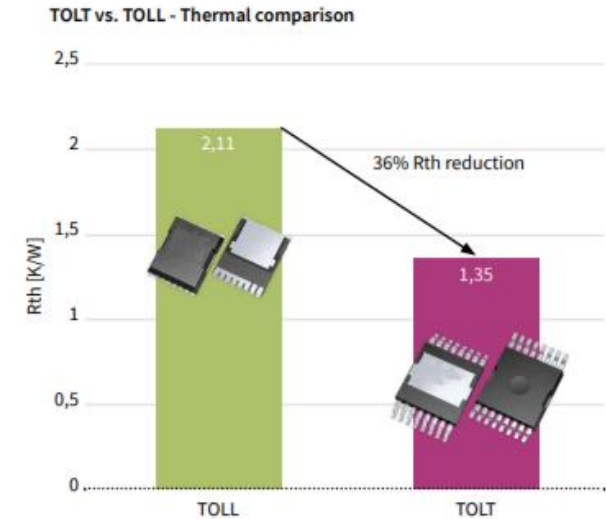
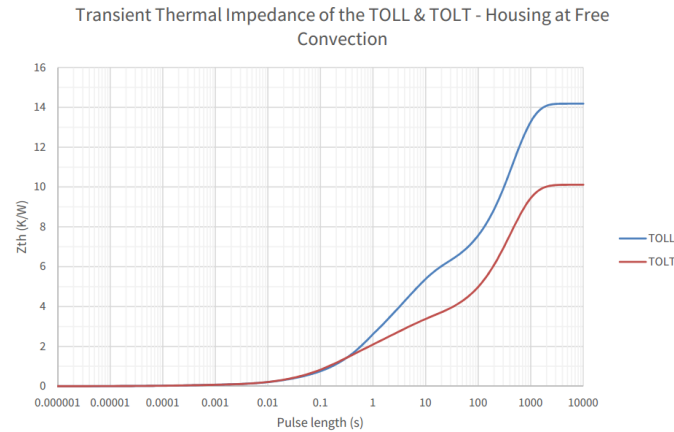
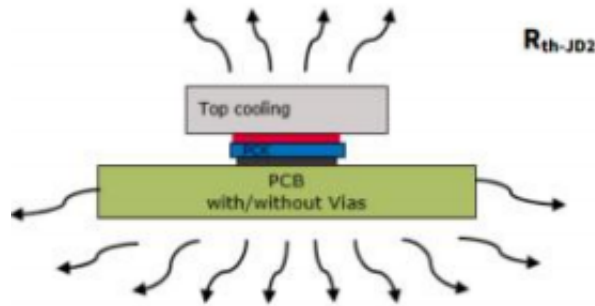
Advantages

- Increased system efficiency enabling extended battery life time
- High power density
- Small profile, high current
- Superior thermal performance



Advantages

- Saving in cooling system
- Minimized thermal resistance to heatsink, R_{thJA} 20% lower, R_{thJC} 50% improved, $R_{th}(J\text{-heatsink})$ 36% reduced, increase the current capability



TOLT are ideal for applications which require high thermal performance, big current and small profile.

E scooter



LEV



Power Tools

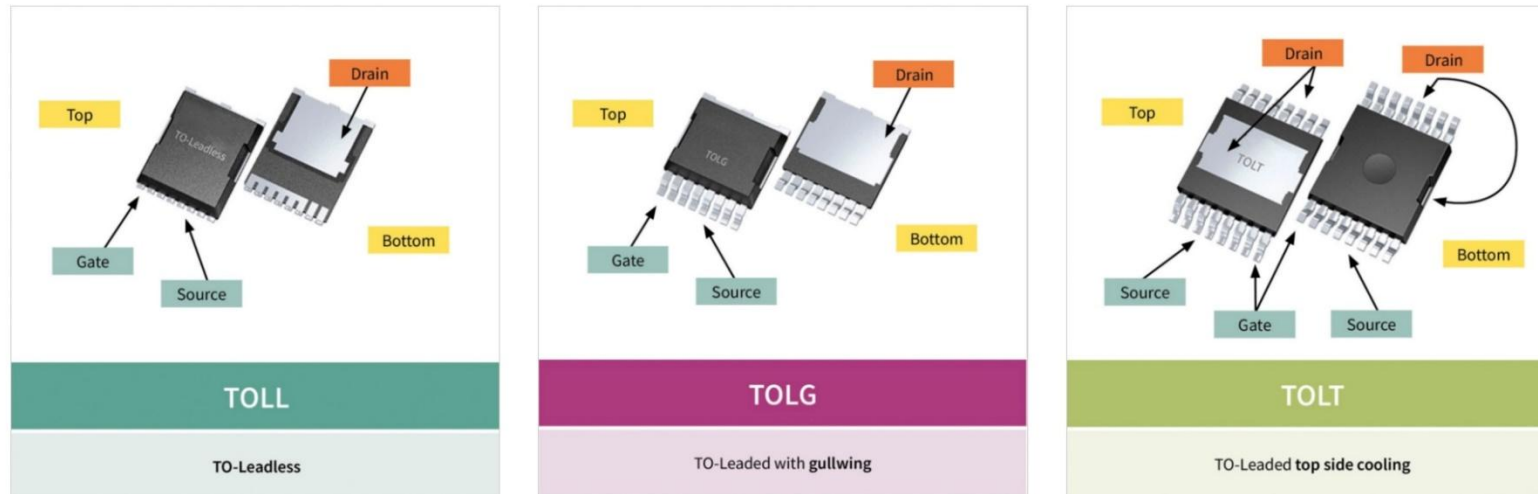


BMS



Development of Toll package

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- The TO-Leaded Topside cooling (TOLT) package expands the high-performance package line of the Power MOSFET family.
- The TOLT package is indeed a significant advancement in power MOSFET technology. It retains the high current and low profile benefits of the TOLL package, but with the added advantage of top-side cooling. This feature allows for superior thermal performance, which is crucial in high-power applications.
- This innovative packaged is a key feature that enables high current ratings greater than 300 A for high power density designs.

THANK YOU

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